

Discription

The HESD5V0D3-TP protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



SOD-323

Features

★ Unidirectional ESD protection of one line

★ Reverse stand-off voltage: 5.0V Max

★ Low leakage current: uA Level

★ Response time is typically < 1 us

★ Low clamping voltage: V_C = 20 V @ I_{PP} = 20 A

★ ESD Protection: 30kV(air)/ 30kV(contact) (IEC61000-4-2)

★ RoHS compliant



Circuit Diagram

Orderingin formation

Product ID	Pack	Qty(PCS)
HESD5V0D3-TP	SOD-323	3000

Absolute Ratings(Tamb = 25°C)

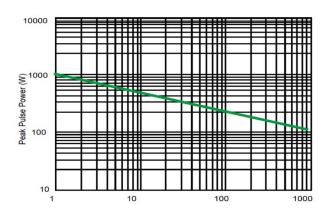
Symbol	Parameter	Value	Units	
P_PP	Peak Pulse Power (t _p = 8/20 μ s)	350	W	
T _L	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +155	°C	
T_{op}	Operating Temperature Range	-40 to +125	°C	
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air disch contact disch	_	±30 ±30	KV

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

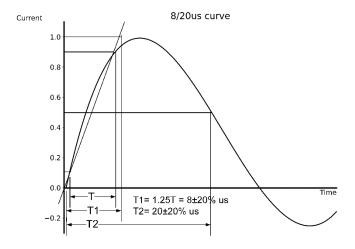
V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	Ι _τ	V _C (V) @ I _{PP} =1 A*	V _C (V) @ Max I _{PP} *	I _{PP} (A)*	P _{PK} (W)*	C (pF)
Max	Max	Min	mA	Тур	Max	Max	Max	Max
5.0	1.0	6.5	1	9	20	20	350	300

^{*}Surge current waveform per Figure 1.

Typical Characteristics (T_A=25°C unless otherwise Specified)



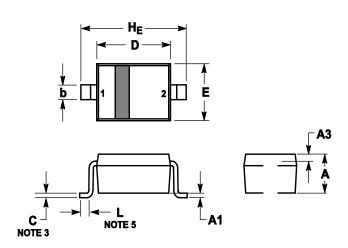




^{1.} V_{BR} is measured with a pluse test current I_T at an ambient temperature of 25 $^\circ\!\!\!\!\!$ C .



Outline And Dimensions

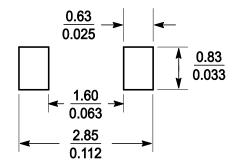


Notes:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MIL	LIMETE	ERS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.8	0.9	1	0.031	0.035	0.04	
A1	0	0.05	0.1	0	0.002	0.004	
А3	0.15REF			0.006REF			
b	0.25	0.32	0.4	0.01	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.6	1.7	1.8	0.062	0.066	0.07	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
H _E	2.3	2.5	2.7	0.09	0.098	0.105	

Soledering Footprint



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